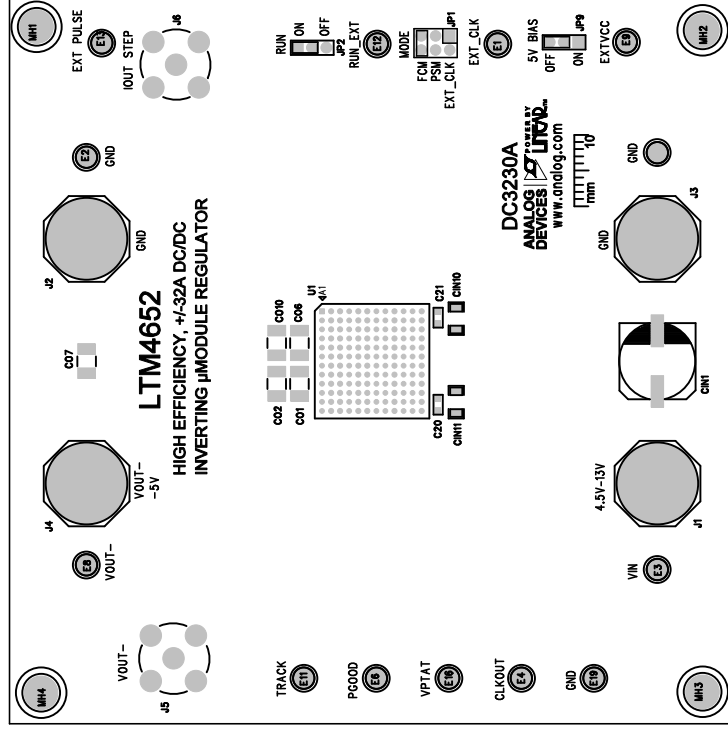
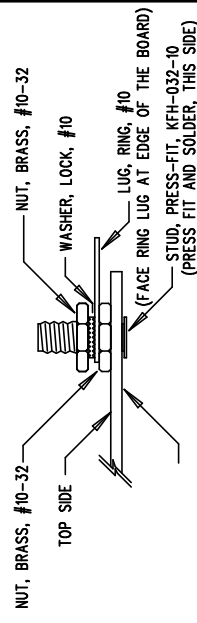
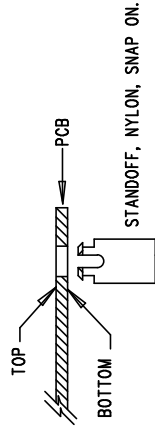




REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	2	PRODUCTION	JL	3-9-22

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AS SHOWN.



SILKSCREEN TOP

APPROVALS		 ANALOG DEVICES www.analog.com	 POWER BY LINEAR™
PCB DES.	Hz		
APP ENG.	Ling J.		
TITLE: TOP ASSEMBLY DRAWING HIGH EFFICIENCY, +/-32A DC/DC INVERTING μ MODULE REGULATOR			
SIZE	IC NO.	LTM4652EY	REV.
N/A	DEMO CIRCUIT 3230A		2
SCALE = NONE		FILENAME: DC3230A-2.PCB SHT 1 OF 2	